

Appl. No. 09/699,897

In the Specification

Please replace the paragraph beginning at page 7, line 17 with the following paragraph:

After maintaining the cold worked component blank at the described temperature, the component blank may be air cooled to 20°C (68°F) or another desired temperature. Alternatively, the component blank may be quenched to a temperature less than the minimum recrystallization temperature. A suitable heat treating temperature may be between about 371°C (700°F) to about ~~[[1200]]~~ 649°C (~~[[649]]~~ 1200°F) or, preferably, between about 427°C (800°F) to about 482°C (900°F). The range of 800°F to 900 °F is particularly suitable for a sputter target blank consisting essentially of nickel.